

# MECHANICAL CASE OUTLINE

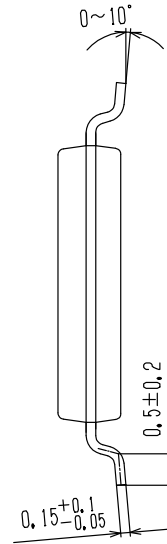
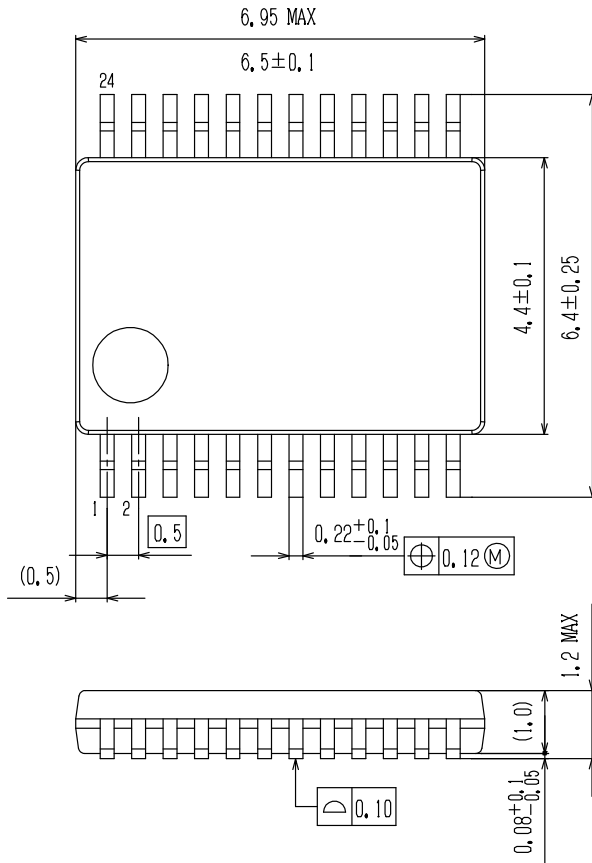
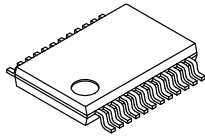
## PACKAGE DIMENSIONS

ON Semiconductor®

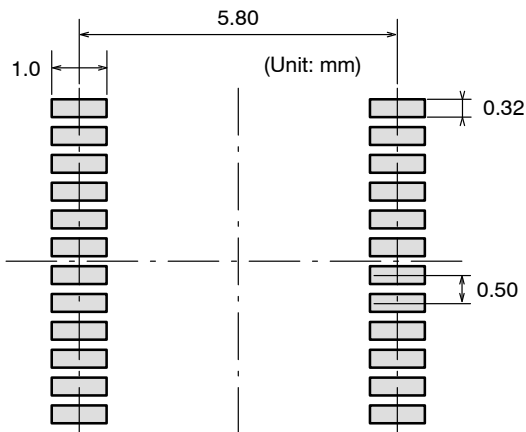


### TSSOP24 4.4x6.5 / TSSOP24 (225 mil) CASE 948BA ISSUE A

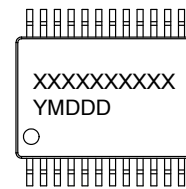
DATE 23 OCT 2013



#### SOLDERING FOOTPRINT\*



#### GENERIC MARKING DIAGRAM\*



XXXXX = Specific Device Code  
Y = Year  
M = Month  
DDD = Additional Traceability Data

NOTE: The measurements are not to guarantee but for reference only.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present.

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<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>TSSOP24 4.4X6.5 / TSSOP24 (225 MIL)</b>	<b>PAGE 1 OF 2</b>

